

#### ABSTRACT OF THE DISCLOSURE

In the case where a first semiconductor chip 100 and a second semiconductor chip 200 are stacked, both the semiconductor chips 100 and 200 are connected using micro bumps, in which a circuit block in the first semiconductor chip and a circuit block in the second semiconductor chip are connected by the micro bumps, and the circuit block in the second semiconductor chip is also connected to the external electrode by the micro bumps through the first semiconductor chip. Further, micro bumps 121, 221 that connect circuit blocks 101, 102, 103, 104 and 210 of both the semiconductor chips 100, 200 and the micro bumps 122, 222 that connect the circuit block 210 in one chip 200 to an external electrode are arranged in different positions.